2SK3044

Silicon N-Channel Power F-MOS FET

■ Features

- Avalanche energy capacity guaranteed: EAS > 130mJ
- \bullet V_{GSS} = ±30V guaranteed
- \bullet High-speed switching: $t_f = 50$ ns
- No secondary breakdown

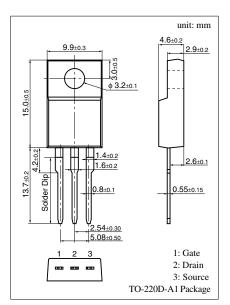
Applications

- Contactless relay
- Diving circuit for a solenoid
- Driving circuit for a motor
- Control equipment
- Switching power supply

■ Absolute Maximum Ratings $(T_C = 25^{\circ}C)$

Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V _{DSS}	450	V	
Gate to Source voltage		V _{GSS}	±30	V	
Drain current	DC	I_D	±7	A	
	Pulse	I_{DP}	±14	A	
Avalanche energy capacity		EAS*	100	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	40	W	
dissipation	Ta = 25°C	$P_{\rm D}$	2		
Channel temperature		T _{ch}	150	°C	
Storage temperature		T _{stg}	-55 to +150	°C	

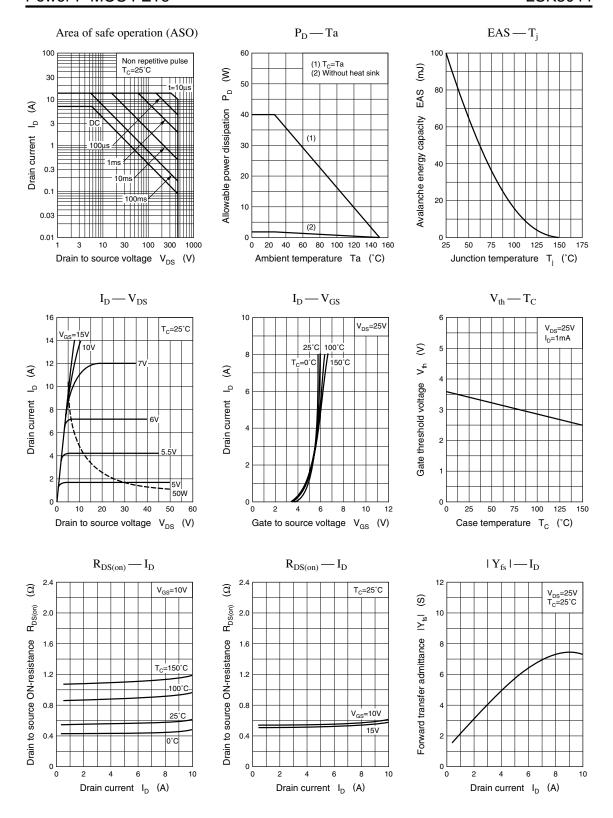
^{*} L = 4.1 mH, $I_L = 8 \text{A}$, $V_{DD} = 50 \text{V}$, 1 pulse



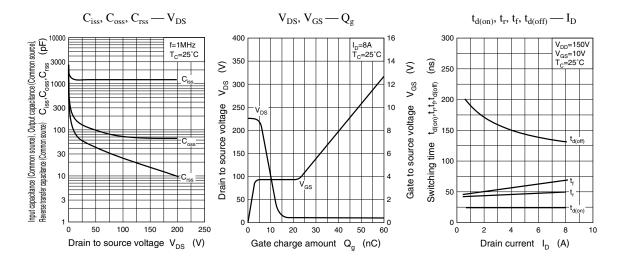
■ Electrical Characteristics ($T_C = 25$ °C)

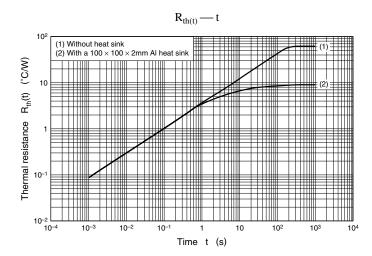
Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	$V_{DS} = 360V, V_{GS} = 0$			0.1	mA
Gate to Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0$			±1	μA
Drain to Source breakdown voltage	V _{DSS}	$I_D = 1 \text{mA}, V_{GS} = 0$	450			V
Gate threshold voltage	V _{th}	$V_{DS} = 25V$, $I_D = 1mA$	2		5	V
Drain to Source ON-resistance	R _{DS(on)}	$V_{GS} = 10V, I_D = 4A$		0.56	0.75	Ω
Forward transfer admittance	Y _{fs}	$V_{DS} = 25V, I_{D} = 4A$	3	5		S
Diode forward voltage	V _{DSF}	$I_{DR} = 8A, V_{GS} = 0$			-1.7	V
Input capacitance (Common Source)	C _{iss}			1300		pF
Output capacitance (Common Source)	Coss	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$		160		pF
Reverse transfer capacitance (Common Source)	C _{rss}			70		pF
Turn-on time (delay time)	t _{d(on)}			25		ns
Rise time	t _r	$V_{GS} = 10V, I_D = 4A$		45		ns
Turn-off time (delay time)	t _{d(off)}	$V_{DD} = 150V, R_L = 37.5\Omega$		150		ns
Fall time	t _f			50		ns

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